

## Accepted Manuscript

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PII: S0040-6031(17)30105-3  
DOI: <http://dx.doi.org/doi:10.1016/j.tca.2017.04.012>  
Reference: TCA 77731

To appear in: *Thermochimica Acta*

Received date: 11-11-2016  
Revised date: 10-4-2017  
Accepted date: 26-4-2017

Please cite this article as: So Youn Mun, Kwang Yeon cho, Doojin Lee, Hyung Mi Lim, Thermal and electrical properties of SiO<sub>2</sub>/SiC-epoxy composite by surface oxidation of silicon carbide, *Thermochimica Acta* <http://dx.doi.org/10.1016/j.tca.2017.04.012>

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## Thermal and electrical properties of SiO<sub>2</sub>/SiC-epoxy composite by surface oxidation of silicon carbide

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### Abstract

SiO<sub>2</sub>/SiC core-shell hybrid was prepared by oxidation of silicon carbide fibers. The material was thermally oxidized to observe the oxidation layer on the surface of the silicon carbide. The electrical and thermal properties of the epoxy composites consisting of SiC or SiO<sub>2</sub>/SiC were investigated. The thermal conductivity of SiO<sub>2</sub>/SiC-epoxy composites increased with increasing oxidation temperature. The thermal conductivity of the SiO<sub>2</sub>/SiC-epoxy composite was higher than that of the SiC-epoxy composite. The surface resistance and breakdown strength of the epoxy composite containing SiO<sub>2</sub>/SiC increased after the thermal oxidation of SiC. The developed SiO<sub>2</sub>/SiC could be used for electronic packaging applications.

### Highlights

- Simple oxidation process produces fibrous SiO<sub>2</sub>/SiC filler for epoxy composites
- Thermal conductivity and electrical insulation increased with treatment temperature (SiO<sub>2</sub> thickness)
- Thermal conductivity and electrical insulation of oxidized fiber composite higher than that of SiC-epoxy one
- Increased thermal conductivity due to improved interfacial interactions

Keywords : thermal property, electrical property, silicon carbide, surface oxidation, electronic packaging

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### 1. Introduction

A major bottleneck in the development of effective electronic packaging is thermal management [1]. Efficient thermal management requires high-performance thermal interface materials that have

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